T529 Series Small Case Size Substrate Terminal Polymer Tantalum



Overview

The KEMET Low ESR Polymer Series is a tantalum capacitor with a Ta anode and ${\rm Ta_2O_5}$ dielectric. A conductive organic polymer replaces the traditionally used ${\rm MnO_2}$ as the cathode plate of the capacitor. This results in very low ESR and improved capacitance retention at high frequency. The KO-CAP also exhibits a benign failure mode which eliminates the ignition failures that can occur in standard ${\rm MnO_2}$ tantalum types. KO-CAPs may also be operated at voltages up to 90% of rated voltage for part types with rated voltages of \leq 10 volts and up to 80% of rated voltage for part types > 10 volts with equivalent or better reliability than traditional ${\rm MnO_2}$ tantalum capacitors operated at 50% of rated voltage.

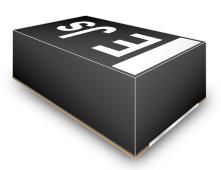
The T529 Series KO-CAP uses a substrate termination design, which results in the most volumetrically efficient packaging technology available today in Polymer Tantalum Chip Capacitors. This series offers high capacitance values in a small 2012-10 (2.0 mm (L) x 1.2 mm (W) x 1.0 mm (H)) package size. The T529 Series is ideal for use in densely populated circuits such as smart phones and digital cameras where space restrictions do not allow for larger and more commonly available case sizes.

Benefits

- · Polymer cathode technology
- Substrate Termination
- EIA Case Size: 2012 (0805 MLCC Equivalent)
- · Low Profile: 1.0 mm maximum
- · Non-ignition failure mode
- · Improved volumetric efficiency
- · Self-healing mechanism
- Capacitance: 22 uF to 150 uF
- Use up to 90% of rated voltage (10% derating)
- Voltage: 6.3 V and 10 V
- RoHS Compliant and Halogen Free
- 105°C maximum temperature capability
- · Lead free 260°C reflow capable

Applications

Typical applications include densely populated circuits where space restrictions do not allow for larger and more commonly available case sizes such as smart phones, digital cameras, MP3 players, GPS navigation systems, WiFi modules, analytical and test equipment, and audio/sound circuits.



Environmental Compliance

RoHS Compliant (6/6) according to Directive 2002/95/EC. Halogen free.







Ordering Information

Т	529	Р	476	M	006	Α	Α	E200
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Failure Rate/ Design	Lead Material	ESR Code
T = Tantalum	529 = Substrate Terminal Polymer	P = 2012-10 I = 3216-10	First two digits represent significant figures. Third digit specifies number of zeros. e.g., 476 = 47 µF	M = ±20%	006 = 6.3 V 010 = 10 V	A = N/A	A = Ni - Au	E = ESR Last three digits specify ESR in mΩ (200 = 200 mΩ)

Performance Characteristics

Item	Specifications
Operating Temperature	-55°C to 105°C
Rated Capacitance Range	22 μF to 150 μF @ 120 Hz/25°C
Capacitance Tolerance	M Tolerance (20%)
Rated Voltage Range	6.3 V and 10 V
DF (120 Hz)	Refer to Part Number Electrical Specification Table
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	Refer to Part Number Electrical Specification Table

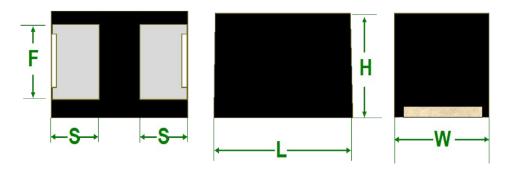


Qualification

Test	Condition/Characteristics					
		Δ C/C	Within initial Δ C/C limits			
Endurance	85°C @ rated voltage, 1,000 hours		DF	Within 1.5 x initial lim	its	
			DCL	Within 3.0 x initial lim	its	
			Δ C/C	-20% to +30% of initia	I Δ C/C limit	
Damp Heat Steady State	40°C, 90 to 95% RH, 500 hours		DF	Within 1.5 x initial lim	its	
		DCL	Within 3.0 x initial lim	its		
			+25°C	-55°C	+105°C	
Townson town Otal 1994	Extreme temperature exposure at -55°C and +105°C	Δ C/C	IL*	-20% to 0% of Δ C/C	-50% - 0% of Δ C/C	
Temperature Stability		DF	IL	IL	IL	
		DCL	IL	IL	1.25 CV	
		,	Δ C/C	Within initial Δ C/C limits		
Surge Voltage	1.3 Vr, 85°C, 1,000 Ω resistor, 1,000 c	DF	Within initial limit			
		DCL	Within initial limit			
			Δ C/C	Within initial Δ C/C lim	nits	
Mechanical Shock	100 G, Saw-Tooth wave		DF	Within initial limit		
			DCL	Within initial limit		
	Frequency: 10 to 2 kHz, Sweep: 1 min	ute	Δ C/C	Within initial Δ C/C lim	nits	
Vibration	Amplitude of vibration: 1.5 mm, Vibrat	DF	Within initial limit			
	Each plane shall be 2 hours for a total	DCL	Within initial limit			
Terminal strength	Strength: 4.9 N, Time: 10 ±0.5 second (two directions)	ds	Visual	No evidence of mechanical damage		

^{*}IL = Initial limit

Dimensions - Millimeters



Case	Size	Component						
KEMET	EIA	L	W	W H		S		
Р	2012–10	2.0 ±0.1	1.25 ±0.1	1.0 maximum	0.9 ±0.1	0.55 ±0.1		
I	3216–10	3.2 ±0.2	1.6 ±0.2	1.0 maximum	1.2 ±0.1	0.8 ±0.1		



Table 1 – Ratings & Part Number Reference

Rated Voltage	Rated Capacitance	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR	Maximum Allowable Ripple Current	Moisture Sensitivity	Rated Temp.
VDC	μF	KEMET/EIA	(See below for part options)	μΑ @ +25°C Maximum/ 5 Minutes	% @ +25°C 120 Hz Maximum	mΩ @ +25°C 100 kHz Maximum	(mA) +45°C 100 kHz	Temp ≤ 260°C	°C
6.3	22	P/2012-10	T529P226M006AAE200	22.0	6	200	548	3	105
6.3	47	P/2012-10	T529P476M006AAE200	29.6	6	200	510	3	105
6.3	47	P/2012-10	T529P476M006AAE150	29.6	6	150	590	3	105
6.3	150	1/3216-10	T529I157M006AAE200	283.5	10	200	548	3	105
6.3	150	1/3216-10	T529I157M006AAE100	283.5	10	100	775	3	105
6.3	150	1/3216-10	T529I157M006AAE070	283.5	10	70	926	3	105
10	22	P/2012-10	T529P226M010AAE200	33.0	6	200	354	3	105
10	47	P/2012-10	T529P476M010AAE200	141.0	6	200	510	3	105

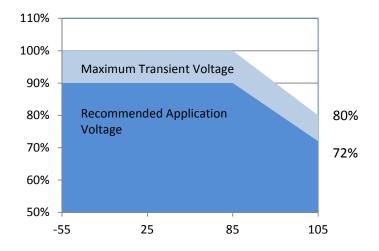
Refer to Ordering Information for additional detail.

Under development

Derating Guidelines

	-55°C t	o 85°C	85°C to 105°C		
Voltage Rating	Maximum Recommended Steady State Voltage	Maximum Recommended Transient Voltage (1 ms – 1 µs)	Maximum Recommended Steady State Voltage	Maximum Recommended Transient Voltage (1 ms – 1 µs)	
≤ 10 V	90% of $V_{\rm R}$	V_R	See Chart	See Chart	

V_R = Rated Voltage





Ripple Current/Ripple Voltage

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

- 1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.
- 2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

Temperature Compensation Multipliers for Maximum Power Dissipation							
T ≤ 45°C	45°C < T ≤ 85°C	85°C < T ≤ 105°C					
1.00	0.90	0.40					

T= Environmental Temperature

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

 $I(max) = \sqrt{P max/R}$ $E(max) = Z \sqrt{P max/R}$

I = rms ripple current (amperes)

E = rms ripple voltage (volts)

P max = maximum power dissipation(watts)

R = ESR at specified frequency (ohms)

Z = Impedance at specified frequency (ohms)

Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts @ 45°C with +30°C Rise		
I	3216	60		
Р	2012	25		

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.



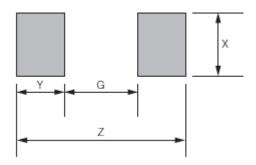
Reverse Voltage

Polymer tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected in the wrong polarity. These devices will withstand a small degree of transient voltage reversal for short periods as shown in the below table.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
55°C	10% of Rated Voltage
85°C	5% of Rated Voltage
105°C	3% of Rated Voltage
125°C*	1% of Rated Voltage

^{*}For Series Rated to 125°C

Table 2 – Land Dimensions/Courtyard



KEMET	Metric Size Code	Dimensions in mm							
Case	EIA	G Maximum	Z Minimum	X Minimum	Y ref				
I	3216–10	1.65	3.25	1.10	0.80				
Р	2012–10	1.05	2.05	0.80	0.50				



Soldering Process

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Please note that although the X/7343–43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

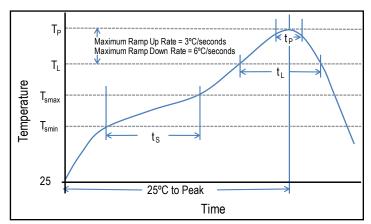
Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

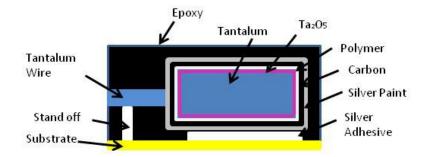
Profile Feature	SnPb Assembly	Pb-Free Assembly		
Preheat/Soak				
Temperature Minimum (T _{Smin})	100°C	150°C		
Temperature Maximum (T _{Smax})	150°C	200°C		
Time (t_s) from T_{smin} to T_{smax})	60 – 120 seconds	60 – 120 seconds		
Ramp-up Rate (T _L to T _P)	3°C/seconds maximum	3°C/seconds maximum		
Liquidous Temperature (T _L)	183°C	217°C		
Time Above Liquidous (t _L)	60 – 150 seconds	60 – 150 seconds		
Peak Temperature (T _P)	220°C* 235°C**	250°C* 260°C**		
Time within 5°C of Maximum Peak Temperature (t _p)	20 seconds maximum	30 seconds maximum		
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/seconds maximum	6°C/seconds maximum		
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum		

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

^{**}Case Size A, B, C, H, I, K, M, R, S, T, U, V, W, and Z



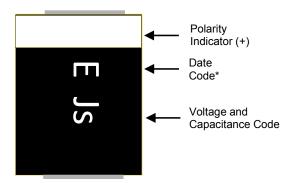
Construction



^{*}Case Size D, E, P, Y, and X



Capacitor Marking



	Date Code *											
	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
2013	А	В	С	D	E	F	G	Н	J	K	L	М
2014	N	Р	Q	R	S	Т	U	V	W	Х	Υ	Z
2015	а	b	С	d	е	f	g	h	j	k	ı	m
2016	n	р	q	r	s	t	u	v	w	х	у	z

Code	J	Α
Rated Voltage	6 V	10 V

Code	j	s	a
Capacitance	22	47	100

Storage

All KO-CAP Series are shipped in moisture barrier bags with a desiccant and moisture indicator card. These series are classified as MSL3 (Moisture Sensitivity Level 3). Product contained within the moisture barrier bags should be stored in normal working environments with temperatures not to exceed 30°C and humidity not in excess of 60% RH.



Tape & Reel Packaging Information

KEMET's molded tantalum and aluminum chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481–1*: Embossed Carrier Taping of Surface Mount Components for Automatic Handling. This packaging system is compatible with all tape-fed automatic pick-and-place systems.

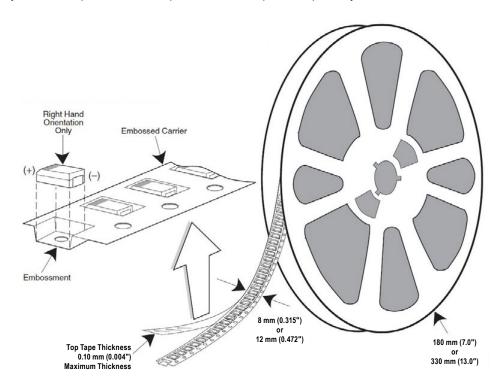


Table 3 – Packaging Quantity

WENT On a Onlar		Tape and Reel Dimensions		
KEMETC	ase Codes	Tape Width (mm)	180 mm (7" diameter)	
I	3216	8	3,000	
Р	2012	8	3,000	

(Quantity per reel)



Figure 1 – Embossed (Plastic) Carrier Tape Dimensions

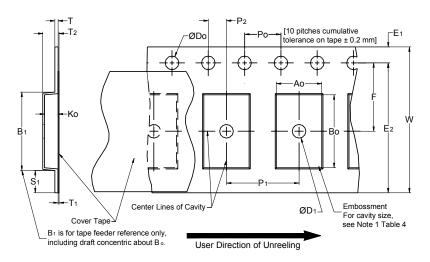


Table 4 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D ₀	D ₁ Minimum Note 1	E ₁	P ₀	P ₂	R Reference Note 2	S ₁ Minimum Note 3	T Maximum	T ₁ Maximum
8 mm	4.5.040/00	1.0 (0.039)	4.75 0.40	40.040	0.0.005	25.0 (0.984)	0.000	0.000	0.400
12 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.5	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm		(0.059)				(1.181)			
			Variable Dim	ensions — M	illimeters (Inc	hes)			
Tape Size	Pitch	B ₁ Maximum Note 4	E ₂ Minimum	F	P ₁	T ₂ Maximum	W Maximum	A ₀ , B ₀	, & K ₀
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)		
10 mm	Single (4 mm) &	8.2	10.25	5.5 ±0.05	8.0 ±0.10	4.6	12.3	No	. F
12 mm	Double (8 mm)	(0.323)	(0.404)	(0.217 ±0.002)	(0.315 ±0.004)	(0.181)	(0.484)	INO	e 5
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	16.3 (0.642)		

- 1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
- 2. The tape, with or without components, shall pass around R without damage (see Figure 5).
- 3. If S₄ < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).
- 4. B, dimension is a reference dimension for tape feeder clearance only.
- 5. The cavity defined by A_{α} , B_{α} and K_{α} shall surround the component with sufficient clearance that:
 - (a) the component does not protrude above the top surface of the carrier tape.
 - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
 - (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).
 - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).
 - (e) see Addendum in EIA Standard 481-D for standards relating to more precise taping requirements.



Packaging Information Performance Notes

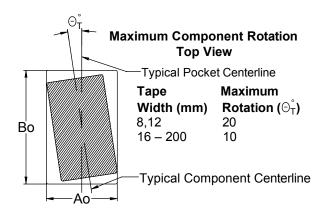
- 1. Cover Tape Break Force: 1.0 Kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ± 10 mm/minute.

3. Labeling: Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624.*

Figure 2 – Maximum Component Rotation



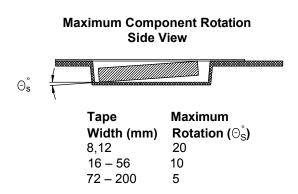


Figure 3 – Maximum Lateral Movement

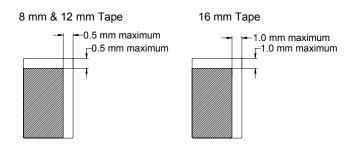


Figure 4 - Bending Radius

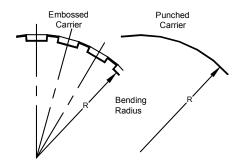
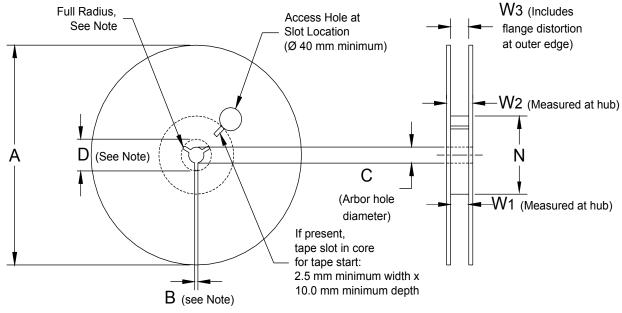




Figure 5 – Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 5 - Reel Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)					
Tape Size	A	B Minimum	С	D Minimum		
8 mm	178 ±0.20 (7.008 ±0.008)					
12 mm	or	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)		
16 mm	330 ±0.20 (13.000 ±0.008)	(0.000)	(0.021 0.02, 0.000)	(* 55)		
	Variable	Dimensions — Millimeter	rs (Inches)			
Tape Size	N Minimum	W ₁	W ₂ Maximum	W_3		
8 mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)			
12 mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference		
16 mm	. ,	16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)			



Figure 6 – Tape Leader & Trailer Dimensions

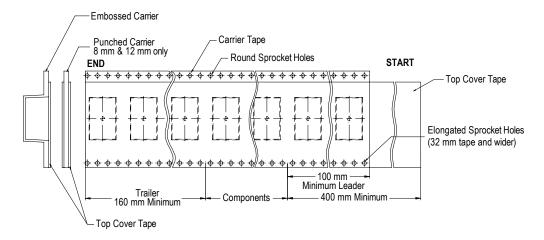
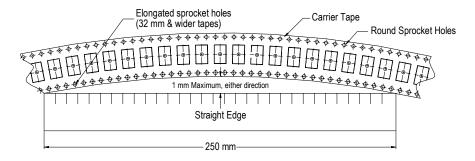


Figure 7 – Maximum Camber





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Kamen, Germany Tel: 49-2307-438110

Northern Europe

Bishop's Stortford, United Kingdom Tel: 44-1279-460122

Espoo, Finland

Tel: 358-9-5406-5000

Asia

Northeast Asia

Hong Kong

Tel: 852-2305-1168

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Beijing, China

Tel: 86-10-5829-1711

Shanghai, China Tel: 86-21-6447-0707

Taipei, Taiwan Tel: 886-2-27528585

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Other KEMET Resources

Tools			
Resource	Location		
Configure A Part: CapEdge	http://capacitoredge.kemet.com		
SPICE & FIT Software	http://www.kemet.com/spice		
Search Our FAQs: KnowledgeEdge	http://www.kemet.com/keask		
Electrolytic LifeCalculator	http://www.kemet.com:8080/elc		

Product Information			
Resource	Location		
Products	http://www.kemet.com/products		
Technical Resources (Including Soldering Techniques)	http://www.kemet.com/technicalpapers		
RoHS Statement	http://www.kemet.com/rohs		
Quality Documents	http://www.kemet.com/qualitydocuments		

Product Request		
Resource Location		
Sample Request	http://www.kemet.com/sample	
Engineering Kit Request	http://www.kemet.com/kits	

Contact			
Resource	Location		
Website	www.kemet.com		
Contact Us	http://www.kemet.com/contact		
Investor Relations	http://www.kemet.com/ir		
Call Us	1-877-MyKEMET		
Twitter	http://twitter.com/kemetcapacitors		

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Although KEMET designs and manufactures its products to the most stringent quality and safety standards, given the current state of the art, isolated component failures may still occur. Accordingly, customer applications which require a high degree of reliability or safety should employ suitable designs or other safeguards (such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury or property damage.

Although all product—related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicted or that other measures may not be required.